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Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

•XFI

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	CANbus, I ² C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	21
Program Memory Size	512KB (170K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	24K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VQFN Exposed Pad
Supplier Device Package	28-QFN-S (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep512gp502-e-mm

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

TABLE 4-39: PMD REGISTER MAP FOR dsPIC33EPXXXGP50X DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
PMD1	0760	T5MD	T4MD	T3MD	T2MD	T1MD				I2C1MD	U2MD	U1MD	SPI2MD	SPI1MD	—	C1MD	AD1MD	0000
PMD2	0762		_	_	-	IC4MD	IC3MD	IC2MD	IC1MD	_	_	_	_	OC4MD	OC3MD	OC2MD	OC1MD	0000
PMD3	0764	_	_	_	_	_	CMPMD			CRCMD	_	—	—		—	I2C2MD		0000
PMD4	0766	_	_	_	_	_	_			_	_	—	—	REFOMD	CTMUMD			0000
PMD6	076A	_		_	_	_				_		—	_		—			0000
													DMA0MD					
PMD7	076C												DMA1MD	PTGMD				0000
FIND7	0700	_	_	_	_	_	_	_	_	_	—	_	DMA2MD	FIGND	_	_	_	0000
													DMA3MD					

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-40: PMD REGISTER MAP FOR dsPIC33EPXXXMC50X DEVICES ONLY

File Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
PMD1	0760	T5MD	T4MD	T3MD	T2MD	T1MD	QEI1MD	PWMMD	_	I2C1MD	U2MD	U1MD	SPI2MD	SPI1MD	—	C1MD	AD1MD	0000
PMD2	0762	_	—	—	—	IC4MD	IC3MD	IC2MD	IC1MD	_	—	—	_	OC4MD	OC3MD	OC2MD	OC1MD	0000
PMD3	0764	_	_	_	_	_	CMPMD	_	_	CRCMD	_	_	_	_	_	I2C2MD	_	0000
PMD4	0766	_	_	_	_	_	_	_	_	_	_	_	_	REFOMD	CTMUMD	_	_	0000
PMD6	076A	_	—		_	_	PWM3MD	PWM2MD	PWM1MD	—			_	—		—	-	0000
													DMA0MD					
PMD7	076C												DMA1MD	PTGMD				0000
FIVID7	0700	_	_	_	_	_	_	_	_	—	_	_	DMA2MD	FIGND	_	_	_	0000
													DMA3MD					

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

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	Vector	IRQ		Inte	errupt Bit L	ocation
Interrupt Source	#	#	IVT Address	Flag	Enable	Priority
	High	est Natura	I Order Priority			
INT0 – External Interrupt 0	8	0	0x000014	IFS0<0>	IEC0<0>	IPC0<2:0>
IC1 – Input Capture 1	9	1	0x000016	IFS0<1>	IEC0<1>	IPC0<6:4>
OC1 – Output Compare 1	10	2	0x000018	IFS0<2>	IEC0<2>	IPC0<10:8>
T1 – Timer1	11	3	0x00001A	IFS0<3>	IEC0<3>	IPC0<14:12>
DMA0 – DMA Channel 0	12	4	0x00001C	IFS0<4>	IEC0<4>	IPC1<2:0>
IC2 – Input Capture 2	13	5	0x00001E	IFS0<5>	IEC0<5>	IPC1<6:4>
OC2 – Output Compare 2	14	6	0x000020	IFS0<6>	IEC0<6>	IPC1<10:8>
T2 – Timer2	15	7	0x000022	IFS0<7>	IEC0<7>	IPC1<14:12>
T3 – Timer3	16	8	0x000024	IFS0<8>	IEC0<8>	IPC2<2:0>
SPI1E – SPI1 Error	17	9	0x000026	IFS0<9>	IEC0<9>	IPC2<6:4>
SPI1 – SPI1 Transfer Done	18	10	0x000028	IFS0<10>	IEC0<10>	IPC2<10:8>
U1RX – UART1 Receiver	19	11	0x00002A	IFS0<11>	IEC0<11>	IPC2<14:12>
U1TX – UART1 Transmitter	20	12	0x00002C	IFS0<12>	IEC0<12>	IPC3<2:0>
AD1 – ADC1 Convert Done	21	13	0x00002E	IFS0<13>	IEC0<13>	IPC3<6:4>
DMA1 – DMA Channel 1	22	14	0x000030	IFS0<14>	IEC0<14>	IPC3<10:8>
Reserved	23	15	0x000032			_
SI2C1 – I2C1 Slave Event	24	16	0x000034	IFS1<0>	IEC1<0>	IPC4<2:0>
MI2C1 – I2C1 Master Event	25	17	0x000036	IFS1<1>	IEC1<1>	IPC4<6:4>
CM – Comparator Combined Event	26	18	0x000038	IFS1<2>	IEC1<2>	IPC4<10:8>
CN – Input Change Interrupt	27	19	0x00003A	IFS1<3>	IEC1<3>	IPC4<14:12>
INT1 – External Interrupt 1	28	20	0x00003C	IFS1<4>	IEC1<4>	IPC5<2:0>
Reserved	29-31	21-23	0x00003E-0x000042			_
DMA2 – DMA Channel 2	32	24	0x000044	IFS1<8>	IEC1<8>	IPC6<2:0>
OC3 – Output Compare 3	33	25	0x000046	IFS1<9>	IEC1<9>	IPC6<6:4>
OC4 – Output Compare 4	34	26	0x000048	IFS1<10>	IEC1<10>	IPC6<10:8>
T4 – Timer4	35	27	0x00004A	IFS1<11>	IEC1<11>	IPC6<14:12>
T5 – Timer5	36	28	0x00004C	IFS1<12>	IEC1<12>	IPC7<2:0>
INT2 – External Interrupt 2	37	29	0x00004E	IFS1<13>	IEC1<13>	IPC7<6:4>
U2RX – UART2 Receiver	38	30	0x000050	IFS1<14>	IEC1<14>	IPC7<10:8>
U2TX – UART2 Transmitter	39	31	0x000052	IFS1<15>	IEC1<15>	IPC7<14:12>
SPI2E – SPI2 Error	40	32	0x000054	IFS2<0>	IEC2<0>	IPC8<2:0>
SPI2 – SPI2 Transfer Done	41	33	0x000056	IFS2<1>	IEC2<1>	IPC8<6:4>
C1RX – CAN1 RX Data Ready ⁽¹⁾	42	34	0x000058	IFS2<2>	IEC2<2>	IPC8<10:8>
C1 – CAN1 Event ⁽¹⁾	43	35	0x00005A	IFS2<3>	IEC2<3>	IPC8<14:12>
DMA3 – DMA Channel 3	44	36	0x00005C	IFS2<4>	IEC2<4>	IPC9<2:0>
IC3 – Input Capture 3	45	37	0x00005E	IFS2<5>	IEC2<5>	IPC9<6:4>
IC4 – Input Capture 4	46	38	0x000060	IFS2<6>	IEC2<6>	IPC9<10:8>
Reserved	47-56	39-48	0x000062-0x000074	—	—	—
SI2C2 – I2C2 Slave Event	57	49	0x000076	IFS3<1>	IEC3<1>	IPC12<6:4>
MI2C2 – I2C2 Master Event	58	50	0x000078	IFS3<2>	IEC3<2>	IPC12<10:8>
Reserved	59-64	51-56	0x00007A-0x000084		_	
PSEM – PWM Special Event Match ⁽²⁾	65	57	0x000086	IFS3<9>	IEC3<9>	IPC14<6:4>

TABLE 7-1: INTERRUPT VECTOR DETAILS

Note 1: This interrupt source is available on dsPIC33EPXXXGP50X and dsPIC33EPXXXMC50X devices only.

2: This interrupt source is available on dsPIC33EPXXXMC20X/50X and PIC24EPXXXMC20X devices only.

8.0 DIRECT MEMORY ACCESS (DMA)

- Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to "Direct Memory Access (DMA)" (DS70348) in the "dsPIC33/ PIC24 Family Reference Manual", which is available from the Microchip web site (www.microchip.com).
 - 2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The DMA Controller transfers data between Peripheral Data registers and Data Space SRAM

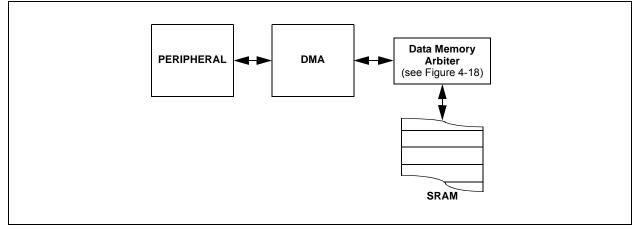
In addition, DMA can access the entire data memory space. The Data Memory Bus Arbiter is utilized when either the CPU or DMA attempts to access SRAM, resulting in potential DMA or CPU stalls.

The DMA Controller supports 4 independent channels. Each channel can be configured for transfers to or from selected peripherals. Some of the peripherals supported by the DMA Controller include:

- ECAN[™]
- Analog-to-Digital Converter (ADC)
- Serial Peripheral Interface (SPI)
- UART
- Input Capture
- Output Compare

Refer to Table 8-1 for a complete list of supported peripherals.

FIGURE 8-1: DMA CONTROLLER MODULE



REGISTE	R 16-7: PWMC	CONX: PWMX (CONTROL R	EGISTER					
HS/HC-	0 HS/HC-0	HS/HC-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0		
FLTSTAT	-(1) CLSTAT ⁽¹⁾	TRGSTAT	FLTIEN	CLIEN	TRGIEN	ITB ⁽²⁾	MDCS ⁽²⁾		
bit 15	·	•		÷			bit		
R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0		
DTC1		DTCP ⁽³⁾	0-0	MTBS	CAM ^(2,4)	XPRES ⁽⁵⁾	IUE ⁽²⁾		
bit 7	DICO								
							bit		
Legend:		HC = Hardware	Clearable bit	HS = Hardwa	are Settable bit				
R = Reada	able bit	W = Writable bi	t	U = Unimple	mented bit, rea	ıd as '0'			
-n = Value	at POR	'1' = Bit is set		'0' = Bit is cle	eared	x = Bit is unk	nown		
bit 15	ELTSTAT: ES	ult Interrupt Statu	is hit(1)						
DIL 15		rrupt is pending							
		interrupt is pendi	ng						
		ared by setting F							
bit 14		rent-Limit Interru	•						
		1 = Current-limit interrupt is pending 0 = No current-limit interrupt is pending							
bit 13	This bit is cleared by setting CLIEN = 0. TRGSTAT: Trigger Interrupt Status bit								
	1 = Trigger interrupt is pending								
		r interrupt is pen							
		ared by setting T							
bit 12		t Interrupt Enable	e bit						
		rrupt is enabled rrupt is disabled	and the FLTS	TAT bit is clear	ed				
bit 11		ent-Limit Interrup			cu .				
		mit interrupt is er							
		mit interrupt is di		e CLSTAT bit is	s cleared				
bit 10	TRGIEN: Trig	ger Interrupt En	able bit						
		event generates			T hit is cleared				
bit 9		vent interrupts ar dent Time Base I			i bit is cleared				
DIL 9		register provides		riad for this PM	VM generator				
		egister provides f	•		•				
bit 8		er Duty Cycle Re							
		ister provides du jister provides du				r			
Note 1:	Software must clea				-		t controller		
Note 1. 2:		-		-	-	the interrup			
3:		nese bits should not be changed after the PWMx is enabled (PTEN = 1). TC<1:0> = 11 for DTCP to be effective; otherwise, DTCP is ignored.							
4:	The Independent T CAM bit is ignored	Time Base (ITB =		•		igned mode. If	TTB = 0, the		
5:	To operate in Exter		t mode, the IT	B bit must be '	1' and the CLM	10D bit in the I	FCLCONx		

REGISTER 16-7: PWMCONx: PWMx CONTROL REGISTER

5: To operate in External Period Reset mode, the ITB bit must be '1' and the CLMOD bit in the FCLCONx register must be '0'.

18.0 SERIAL PERIPHERAL INTERFACE (SPI)

- Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to "Serial Peripheral Interface (SPI)" (DS70569) in the "dsPIC33/PIC24 Family Reference Manual", which is available from the Microchip web site (www.microchip.com).
 - Some registers and associated bits described in this section may not be available on all devices. Refer to Section 4.0 "Memory Organization" in this data sheet for device-specific register and bit information.

The SPI module is a synchronous serial interface, useful for communicating with other peripheral or microcontroller devices. These peripheral devices can be serial EEPROMs, shift registers, display drivers, ADC Converters, etc. The SPI module is compatible with Motorola[®] SPI and SIOP interfaces.

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/ 50X and PIC24EPXXXGP/MC20X device family offers two SPI modules on a single device. These modules, which are designated as SPI1 and SPI2, are functionally identical. Each SPI module includes an eight-word FIFO buffer and allows DMA bus connections. When using the SPI module with DMA, FIFO operation can be disabled.

Note: In this section, the SPI modules are referred to together as SPIx, or separately as SPI1 and SPI2. Special Function Registers follow a similar notation. For example, SPIxCON refers to the control register for the SPI1 and SPI2 modules.

The SPI1 module uses dedicated pins which allow for a higher speed when using SPI1. The SPI2 module takes advantage of the Peripheral Pin Select (PPS) feature to allow for greater flexibility in pin configuration of the SPI2 module, but results in a lower maximum speed for SPI2. See **Section 30.0** "**Electrical Characteristics**" for more information.

The SPIx serial interface consists of four pins, as follows:

- SDIx: Serial Data Input
- SDOx: Serial Data Output
- SCKx: Shift Clock Input or Output
- SSx/FSYNCx: Active-Low Slave Select or Frame Synchronization I/O Pulse

The SPIx module can be configured to operate with two, three or four pins. In 3-pin mode, SSx is not used. In 2-pin mode, neither SDOx nor SSx is used.

Figure 18-1 illustrates the block diagram of the SPIx module in Standard and Enhanced modes.

20.1 UART Helpful Tips

- 1. In multi-node, direct-connect UART networks, receive inputs UART react to the complementary logic level defined by the URXINV bit (UxMODE<4>), which defines the Idle state, the default of which is logic high (i.e., URXINV = 0). Because remote devices do not initialize at the same time, it is likely that one of the devices, because the RX line is floating, will trigger a Start bit detection and will cause the first byte received, after the device has been initialized, to be invalid. To avoid this situation, the user should use a pull-up or pull-down resistor on the RX pin depending on the value of the URXINV bit.
 - a) If URXINV = 0, use a pull-up resistor on the RX pin.
 - b) If URXINV = 1, use a pull-down resistor on the RX pin.
- 2. The first character received on a wake-up from Sleep mode caused by activity on the UxRX pin of the UARTx module will be invalid. In Sleep mode, peripheral clocks are disabled. By the time the oscillator system has restarted and stabilized from Sleep mode, the baud rate bit sampling clock, relative to the incoming UxRX bit timing, is no longer synchronized, resulting in the first character being invalid; this is to be expected.

20.2 UART Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter
	this URL in your browser:
	http://www.microchip.com/wwwproducts/
	Devices.aspx?dDocName=en555464

20.2.1 KEY RESOURCES

- "UART" (DS70582) in the "dsPIC33/PIC24 Family Reference Manual"
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All Related "dsPIC33/PIC24 Family Reference Manual" Sections
- Development Tools

U-0	U-0	U-0	R-0	R-0	R-0	R-0	R-0
_	_		FILHIT4	FILHIT3	FILHIT2	FILHIT1	FILHIT0
bit 15	I	•					bit 8
U-0	R-1	R-0	R-0	R-0	R-0	R-0	R-0
_	ICODE6	ICODE5	ICODE4	ICODE3	ICODE2	ICODE1	ICODE0
bit 7							bit
Logondi							
Legend: R = Readable	- hit		hit.		nonted hit rea	d aa 'O'	
-n = Value at		W = Writable		'0' = Bit is cle	mented bit, rea		
-n = value at	POR	'1' = Bit is set		0 = Bit is cie	ared	x = Bit is unkr	IOWN
bit 15-13	Unimplemen	ted: Read as '	0'				
bit 12-8	=	Filter Hit Num					
		1 = Reserved					
	01111 = Filte	r 15					
	•						
	•						
		- 1					
	00001 = Filte 00000 = Filte						
bit 7		ted: Read as '	0'				
bit 6-0	-	Interrupt Flag					
		11111 = Rese					
		IFO almost full					
		eceiver overflo					
	1000010 = K 1000001 = E	/ake-up interru rror interrupt	μ				
	1000000 = N						
	•						
	•						
	•						
		11111 = Rese					
	•	B15 buffer inte	inupt				
	•						
	•						
	0001001 = R	B9 buffer inter	rupt				
		B8 buffer inter					
		RB7 buffer inte RB6 buffer inte					
		RB5 buffer inte					
		RB4 buffer inte					
	0000011 = T	RB3 buffer inte	errupt				
		RB2 buffer inte RB1 buffer inte					

REGISTER 21-3: CxVEC: ECANx INTERRUPT CODE REGISTER

22.2 **CTMU Control Registers**

REGISTER	22-1: CTM	UCON1: CTM	J CONTROI	- REGISTER	1		
R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CTMUEN	_	CTMUSIDL	TGEN	EDGEN	EDGSEQEN	IDISSEN ⁽¹⁾	CTTRIG
bit 15							bit 8
U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	_		_	<u> </u>	<u> </u>		_
bit 7							bit 0
Legend:							
R = Readable	e bit	W = Writable b	bit	U = Unimplen	nented bit, read	as '0'	
-n = Value at	POR	'1' = Bit is set		'0' = Bit is cle	own		
bit 15		TMU Enable bit is enabled is disabled					
bit 14	Unimpleme	nted: Read as '0	,				
bit 13 CTMUSIDL: CTMU Stop in Idle Mode bit 1 = Discontinues module operation when device enters Idle mode 0 = Continues module operation in Idle mode							
bit 12	TGEN: Time	Generation Ena	ble bit				

DECISTED

bit 9	IDISSEN: Analog Current Source Control bit ⁽¹⁾
	1 = Analog current source output is grounded0 = Analog current source output is not grounded
bit 8	CTTRIG: ADC Trigger Control bit
	1 = CTMU triggers ADC start of conversion0 = CTMU does not trigger ADC start of conversion

EDGSEQEN: Edge Sequence Enable bit

0 = No edge sequence is needed

1 = Enables edge delay generation 0 = Disables edge delay generation

EDGEN: Edge Enable bit

bit 7-0 Unimplemented: Read as '0'

bit 11

bit 10

Note 1: The ADC module Sample-and-Hold capacitor is not automatically discharged between sample/conversion cycles. Software using the ADC as part of a capacitance measurement must discharge the ADC capacitor before conducting the measurement. The IDISSEN bit, when set to '1', performs this function. The ADC must be sampling while the IDISSEN bit is active to connect the discharge sink to the capacitor array.

1 = Hardware modules are used to trigger edges (TMRx, CTEDx, etc.) 0 = Software is used to trigger edges (manual set of EDGxSTAT)

1 = Edge 1 event must occur before Edge 2 event can occur

dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X AND PIC24EPXXXGP/MC20X

R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0		
CH0NB	_	_	CH0SB4 ⁽¹⁾	CH0SB3 ⁽¹⁾	CH0SB2 ⁽¹⁾	CH0SB1 ⁽¹⁾	CH0SB0 ⁽¹⁾		
bit 15	•			•			bit 8		
R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0		
CH0NA			CH0SA4 ⁽¹⁾	CH0SA3 ⁽¹⁾	CH0SA2 ⁽¹⁾	CH0SA1 ⁽¹⁾	CH0SA0 ⁽¹⁾		
bit 7							bit (
Legend:									
R = Read		W = Writable		•	nented bit, read				
-n = Value	e at POR	'1' = Bit is set		'0' = Bit is cle	ared	x = Bit is unkr	iown		
bit 15		nannel 0 Negative	Input Soloot fo	r Samala MUV	'D hit				
DIL 15		el 0 negative input							
		el 0 negative input							
bit 14-13	Unimplem	ented: Read as 'o)'						
bit 12-8	CH0SB<4:	0>: Channel 0 Po	sitive Input Sele	ect for Sample	MUXB bits ⁽¹⁾				
		pen; use this sele				ement			
	11110 = C	nannel 0 positive in	put is connected	to the CTMU te	emperature mea	surement diode	(CTMU TEMF		
	11101 = R								
	11100 = R 11011 = R								
		hannel 0 positive	input is the outr	out of OA3/AN6	₎ (2,3)				
		hannel 0 positive							
	11000 = C	hannel 0 positive	input is the outp	out of OA1/AN3	₃ (2)				
	10111 = R	eserved							
	•								
	•								
	10000 = R	eserved							
	01111 = C	hannel 0 positive	input is AN15 ⁽³⁾						
	01110 = C	hannel 0 positive	input is AN14 ⁽³⁾						
	01101 = C	hannel 0 positive	Input is AN130						
	•								
	•								
	00010 = C	hannel 0 positive	input is AN2 ⁽³⁾						
		hannel 0 positive hannel 0 positive							
L:1 7		•	•		A 64				
bit 7	CH0NA: Channel 0 Negative Input Select for Sample MUXA bit 1 = Channel 0 negative input is AN1 ⁽¹⁾								
		el 0 negative input							
bit 6-5		ented: Read as '							
Note 1:	to determine I	AN7 are repurpos now enabling a pa							
-	and 3.						- >		
2:		t is used if the co		amp is selecte	d (OPMODE (C	MxCON<10>) :	= 1);		

REGISTER 23-6: AD1CHS0: ADC1 INPUT CHANNEL 0 SELECT REGISTER

3: See the "**Pin Diagrams**" section for the available analog channels for each device.

otherwise, the ANx input is used.

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	
PTGCLK2	PTGCLK1	PTGCLK0	PTGDIV4	PTGDIV3	PTGDIV2	PTGDIV1	PTGDIV0	
bit 15	1	1	1		1		bit	
R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0	R/W-0	
PTGPWD3	PTGPWD2	PTGPWD1	PTGPWD0	_	PTGWDT2	PTGWDT1	PTGWDTC	
bit 7							bit	
Legend:								
R = Readable	bit	W = Writable	bit	U = Unimpler	mented bit, read	l as '0'		
-n = Value at F	POR	'1' = Bit is set		'0' = Bit is cle	ared	x = Bit is unkr	nown	
bit 15-13	111 = Reserv 110 = Reserv 101 = PTG m 100 = PTG m 011 = PTG m 010 = PTG m 001 = PTG m		urce will be T3 urce will be T2 urce will be T1 urce will be TA urce will be Fc	SCLK SCLK CLK D DSC				
bit 12-8	<pre>PTGDIV<4:0>: PTG Module Clock Prescaler (divider) bits 11111 = Divide-by-32 11110 = Divide-by-31</pre>							
bit 7-4	PTGPWD<3:0 1111 = All trig 1110 = All trig 0001 = All trig	D>: PTG Trigge gger outputs ar gger outputs ar gger outputs ar	e 16 PTG cloc e 15 PTG cloc e 2 PTG clock	k cycles wide k cycles wide cycles wide				
bit 3	Unimplemen	ted: Read as '	0'					
bit 2-0	Unimplemented: Read as '0' PTGWDT<2:0>: Select PTG Watchdog Timer Time-out Count Value bits 111 = Watchdog Timer will time-out after 512 PTG clocks 110 = Watchdog Timer will time-out after 256 PTG clocks 101 = Watchdog Timer will time-out after 128 PTG clocks 100 = Watchdog Timer will time-out after 64 PTG clocks 011 = Watchdog Timer will time-out after 32 PTG clocks 010 = Watchdog Timer will time-out after 16 PTG clocks 010 = Watchdog Timer will time-out after 8 PTG clocks 001 = Watchdog Timer will time-out after 8 PTG clocks 000 = Watchdog Timer is disabled							

REGISTER 24-2: PTGCON: PTG CONTROL REGISTER

REGISTER 24-3: PTGBTE: PTG BROADCAST TRIGGER ENABLE REGISTER^(1,2) (CONTINUED)

OC1CS: Clock Source for OC1 bit
 1 = Generates clock pulse when the broadcast command is executed 0 = Does not generate clock pulse when the broadcast command is executed
OC4TSS: Trigger/Synchronization Source for OC4 bit
 1 = Generates Trigger/Synchronization when the broadcast command is executed 0 = Does not generate Trigger/Synchronization when the broadcast command is executed
OC3TSS: Trigger/Synchronization Source for OC3 bit
 1 = Generates Trigger/Synchronization when the broadcast command is executed 0 = Does not generate Trigger/Synchronization when the broadcast command is executed
OC2TSS: Trigger/Synchronization Source for OC2 bit
 1 = Generates Trigger/Synchronization when the broadcast command is executed 0 = Does not generate Trigger/Synchronization when the broadcast command is executed
OC1TSS: Trigger/Synchronization Source for OC1 bit
 1 = Generates Trigger/Synchronization when the broadcast command is executed 0 = Does not generate Trigger/Synchronization when the broadcast command is executed

- **Note 1:** This register is read-only when the PTG module is executing Step commands (PTGEN = 1 and PTGSTRT = 1).
 - 2: This register is only used with the PTGCTRL OPTION = 1111 Step command.

30.1 DC Characteristics

			Maximum MIPS
Characteristic	VDD Range (in Volts)	Temp Range (in °C)	dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X
	3.0V to 3.6V ⁽¹⁾	-40°C to +85°C	70
—	3.0V to 3.6V ⁽¹⁾	-40°C to +125°C	60

Note 1: Device is functional at VBORMIN < VDD < VDDMIN. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Device functionality is tested but not characterized. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

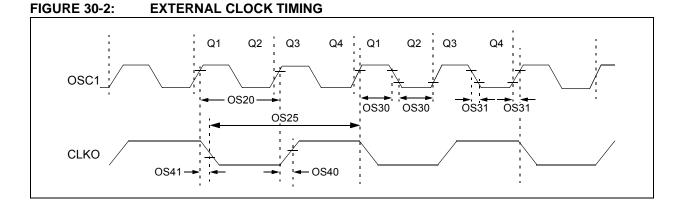
TABLE 30-2: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min.	Тур.	Max.	Unit
Industrial Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+125	°C
Operating Ambient Temperature Range	TA	-40	—	+85	°C
Extended Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+140	°C
Operating Ambient Temperature Range	TA	-40	—	+125	°C
Power Dissipation: Internal chip power dissipation: $PINT = VDD x (IDD - \Sigma IOH)$		I	Pint + Pi/c)	W
I/O Pin Power Dissipation: $I/O = \Sigma (\{VDD - VOH\} x IOH) + \Sigma (VOL x IOL)$					
Maximum Allowed Power Dissipation	PDMAX	(ΓJ — TA)/θJ	IA	W

TABLE 30-3: THERMAL PACKAGING CHARACTERISTICS

Characteristic	Symbol	Тур.	Max.	Unit	Notes
Package Thermal Resistance, 64-Pin QFN	θJA	28.0		°C/W	1
Package Thermal Resistance, 64-Pin TQFP 10x10 mm	θJA	48.3	_	°C/W	1
Package Thermal Resistance, 48-Pin UQFN 6x6 mm	θJA	41	—	°C/W	1
Package Thermal Resistance, 44-Pin QFN	θJA	29.0	_	°C/W	1
Package Thermal Resistance, 44-Pin TQFP 10x10 mm	θJA	49.8	_	°C/W	1
Package Thermal Resistance, 44-Pin VTLA 6x6 mm	θJA	25.2	_	°C/W	1
Package Thermal Resistance, 36-Pin VTLA 5x5 mm	θJA	28.5		°C/W	1
Package Thermal Resistance, 28-Pin QFN-S	θJA	30.0	_	°C/W	1
Package Thermal Resistance, 28-Pin SSOP	θJA	71.0	_	°C/W	1
Package Thermal Resistance, 28-Pin SOIC	θJA	69.7	_	°C/W	1
Package Thermal Resistance, 28-Pin SPDIP	θJA	60.0	—	°C/W	1

Note 1: Junction to ambient thermal resistance, Theta-JA (θ JA) numbers are achieved by package simulations.



		$\begin{array}{l} \mbox{Standard Operating Conditions: 3.0V to 3.6V} \\ \mbox{(unless otherwise stated)} \\ \mbox{Operating temperature} & -40^{\circ}C \leq TA \leq +85^{\circ}C \mbox{ for Industrial} \\ & -40^{\circ}C \leq TA \leq +125^{\circ}C \mbox{ for Extended} \end{array}$					
Param No.	Symb	Characteristic	Min.	Тур. ⁽¹⁾	Max.	Units	Conditions
OS10	Fin	External CLKI Frequency (External clocks allowed only in EC and ECPLL modes)	DC	_	60	MHz	EC
		Oscillator Crystal Frequency	3.5 10		10 25	MHz MHz	XT HS
OS20	Tosc	Tosc = 1/Fosc	8.33	_	DC	ns	+125°C
		Tosc = 1/Fosc	7.14	_	DC	ns	+85°C
OS25	Тсү	Instruction Cycle Time ⁽²⁾	16.67	_	DC	ns	+125°C
		Instruction Cycle Time ⁽²⁾	14.28	_	DC	ns	+85°C
OS30	TosL, TosH	External Clock in (OSC1) High or Low Time	0.45 x Tosc	—	0.55 x Tosc	ns	EC
OS31	TosR, TosF	External Clock in (OSC1) Rise or Fall Time	—	—	20	ns	EC
OS40	TckR	CLKO Rise Time ^(3,4)	—	5.2	_	ns	
OS41	TckF	CLKO Fall Time ^(3,4)	—	5.2		ns	
OS42	Gм	External Oscillator Transconductance ⁽⁴⁾	—	12	_	mA/V	HS, VDD = 3.3V, TA = +25°C
			—	6	_	mA/V	XT, VDD = 3.3V, TA = +25°C

TABLE 30-17: EXTERNAL CLOCK TIMING REQUIREMENTS

Note 1: Data in "Typical" column is at 3.3V, +25°C unless otherwise stated.

- 2: Instruction cycle period (Tcr) equals two times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "Minimum" values with an external clock applied to the OSC1 pin. When an external clock input is used, the "Maximum" cycle time limit is "DC" (no clock) for all devices.
- 3: Measurements are taken in EC mode. The CLKO signal is measured on the OSC2 pin.
- 4: This parameter is characterized, but not tested in manufacturing.

			(unless		se stateo rature	i)⁽¹⁾ -40°C ≤ ⁻	3.0V to 3.6V TA \leq +85°C for Industrial TA \leq +125°C for Extended
Param No.	Symbol	Characteristic	Min.	Тур.	Max.	Units	Conditions
		ADC A	Accuracy	(12-Bit	Mode)		
AD20a	Nr	Resolution	12	2 Data Bi	ts	bits	
AD21a	INL	Integral Nonlinearity	-2.5		2.5	LSb	-40°C ≤ TA ≤ +85°C (Note 2)
			-5.5	_	5.5	LSb	+85°C < TA ≤ +125°C (Note 2)
AD22a	DNL	Differential Nonlinearity	-1	—	1	LSb	-40°C \leq TA \leq +85°C (Note 2)
			-1	—	1	LSb	+85°C < TA \leq +125°C (Note 2)
AD23a	Gerr	Gain Error ⁽³⁾	-10	—	10	LSb	-40°C \leq TA \leq +85°C (Note 2)
			-10	_	10	LSb	+85°C < TA \leq +125°C (Note 2)
AD24a	EOFF	Offset Error	-5	_	5	LSb	$-40^{\circ}C \leq TA \leq +85^{\circ}C \text{ (Note 2)}$
			-5	_	5	LSb	+85°C < TA \leq +125°C (Note 2)
AD25a	—	Monotonicity	—	—	—		Guaranteed
		Dynamic	Performa	ance (12-	Bit Mod	e)	
AD30a	THD	Total Harmonic Distortion ⁽³⁾	_	75	_	dB	
AD31a	SINAD	Signal to Noise and Distortion ⁽³⁾	—	68	_	dB	
AD32a	SFDR	Spurious Free Dynamic Range ⁽³⁾	—	80	—	dB	
AD33a	Fnyq	Input Signal Bandwidth ⁽³⁾	—	250	—	kHz	
AD34a	ENOB	Effective Number of Bits ⁽³⁾	11.09	11.3	_	bits	

TABLE 30-58: ADC MODULE SPECIFICATIONS (12-BIT MODE)

Note 1: Device is functional at VBORMIN < VDD < VDDMIN, but will have degraded performance. Device functionality is tested, but not characterized. Analog modules (ADC, op amp/comparator and comparator voltage reference) may have degraded performance. Refer to Parameter BO10 in Table 30-13 for the minimum and maximum BOR values.

2: For all accuracy specifications, VINL = AVSS = VREFL = 0V and AVDD = VREFH = 3.6V.

3: Parameters are characterized but not tested in manufacturing.

dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X AND PIC24EPXXXGP/MC20X

TABLE 31-11: INTERNAL RC ACCURACY

AC CH	ARACTERISTICS	Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}C \le TA \le +150^{\circ}C$						
Param No.	Characteristic	Min	Тур	Max	Units	Conditions		
	LPRC @ 32.768 kHz ^(1,2)							
HF21	LPRC	-30	_	+30	%	$-40^{\circ}C \leq TA \leq +150^{\circ}C$	VDD = 3.0-3.6V	

Note 1: Change of LPRC frequency as VDD changes.

2: LPRC accuracy impacts the Watchdog Timer Time-out Period (TwDT). See Section 27.5 "Watchdog Timer (WDT)" for more information.

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}C \le TA \le +150^{\circ}C$					
Param No.	Symbol	Characteristic	Min	Тур	Max	Units	Conditions	
ADC Accuracy (12-Bit Mode) ⁽¹⁾								
HAD20a	Nr	Resolution ⁽³⁾	12	2 Data B	its	bits		
HAD21a	INL	Integral Nonlinearity	-5.5	_	5.5	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V	
HAD22a	DNL	Differential Nonlinearity	-1	_	1	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V	
HAD23a	Gerr	Gain Error	-10		10	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V	
HAD24a	EOFF	Offset Error	-5	—	5	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V	
	Dynamic Performance (12-Bit Mode) ⁽²⁾							
HAD33a	Fnyq	Input Signal Bandwidth	_	_	200	kHz		

TABLE 31-12: ADC MODULE SPECIFICATIONS (12-BIT MODE)

Note 1: These parameters are characterized, but are tested at 20 ksps only.

2: These parameters are characterized by similarity, but are not tested in manufacturing.

3: Injection currents > | 0 | can affect the ADC results by approximately 4-6 counts.

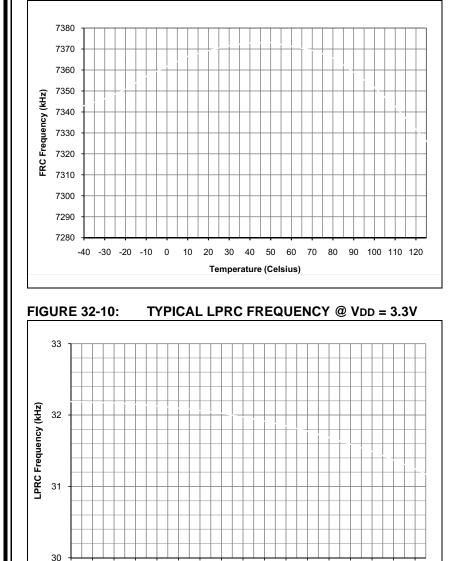
TABLE 31-13: ADC MODULE SPECIFICATIONS (10-BIT MODE)

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}C \le TA \le +150^{\circ}C$					
Param No.	Symbol	Characteristic	Min	Тур	Max	Units	Conditions	
	ADC Accuracy (10-Bit Mode) ⁽¹⁾							
HAD20b	Nr	Resolution ⁽³⁾	10) Data B	its	bits		
HAD21b	INL	Integral Nonlinearity	-1.5	_	1.5	LSb	Vinl = AVss = Vrefl = 0V, AVdd = Vrefh = 3.6V	
HAD22b	DNL	Differential Nonlinearity	-0.25	-	0.25	LSb	Vinl = AVss = Vrefl = 0V, AVdd = Vrefh = 3.6V	
HAD23b	Gerr	Gain Error	-2.5		2.5	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V	
HAD24b	EOFF	Offset Error	-1.25	_	1.25	LSb	VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.6V	
	Dynamic Performance (10-Bit Mode) ⁽²⁾							
HAD33b	Fnyq	Input Signal Bandwidth	_	_	400	kHz		

Note 1: These parameters are characterized, but are tested at 20 ksps only.

2: These parameters are characterized by similarity, but are not tested in manufacturing.

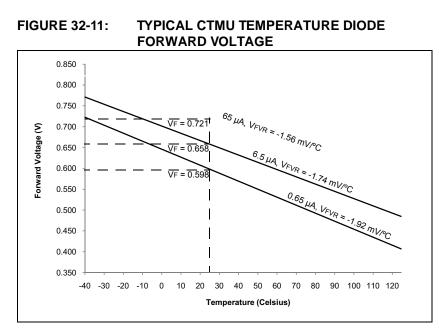
3: Injection currents > | 0 | can affect the ADC results by approximately 4-6 counts.



Temperature (Celsius)

70 80 90 100 110 120

TYPICAL FRC FREQUENCY @ VDD = 3.3V



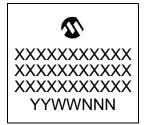
-40 -30 -20 -10

0 10 20 30 40 50 60

FIGURE 32-9:

33.1 Package Marking Information (Continued)

48-Lead UQFN (6x6x0.5 mm)



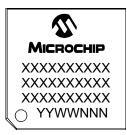
Example 33EP64GP 504-I/MV (3) 1310017

64-Lead QFN (9x9x0.9 mm)



Example dsPIC33EP 64GP506 -I/MR® 1310017

64-Lead TQFP (10x10x1 mm)



Example



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48-Lead Ultra Thin Plastic Quad Flat, No Lead Package (MV) - 6x6 mm Body [UQFN] With 0.40 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	MILLIMETERS			
Dimensior	n Limits	MIN	NOM	MAX
Contact Pitch	E		0.40 BSC	
Optional Center Pad Width	W2			4.45
Optional Center Pad Length	T2			4.45
Contact Pad Spacing	C1		6.00	
Contact Pad Spacing	C2		6.00	
Contact Pad Width (X28)	X1			0.20
Contact Pad Length (X28)	Y1			0.80
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2153A

TABLE A-1: MAJOR SECTION UPDATES (CONTINUED)

Section Name	Update Description
Section 30.0 "Electrical Characteristics"	Removed Voltage on VCAP with respect to Vss and added Note 5 in Absolute Maximum Ratings ⁽¹⁾ .
	Removed Parameter DC18 (VCORE) and Note 3 from the DC Temperature and Voltage Specifications (see Table 30-4).
	Updated Note 1 in the DC Characteristics: Operating Current (IDD) (see Table 30-6).
	Updated Note 1 in the DC Characteristics: Idle Current (IIDLE) (see Table 30-7).
	Changed the Typical values for Parameters DC60a-DC60d and updated Note 1 in the DC Characteristics: Power-down Current (IPD) (see Table 30-8).
	Updated Note 1 in the DC Characteristics: Doze Current (IDOZE) (see Table 30-9).
	Updated Note 2 in the Electrical Characteristics: BOR (see Table 30-12).
	Updated Parameters CM20 and CM31, and added Parameters CM44 and CM45 in the AC/DC Characteristics: Op amp/Comparator (see Table 30-14).
	Added the Op amp/Comparator Reference Voltage Settling Time Specifications (see Table 30-15).
	Added Op amp/Comparator Voltage Reference DC Specifications (see Table 30-16).
	Updated Internal FRC Accuracy Parameter F20a (see Table 30-21).
	Updated the Typical value and Units for Parameter CTMUI1, and added Parameters CTMUI4, CTMUFV1, and CTMUFV2 to the CTMU Current Source Specifications (see Table 30-55).
Section 31.0 "Packaging Information"	Updated packages by replacing references of VLAP with TLA.
"Product Identification System"	Changed VLAP to TLA.